

## 30V N-Channel Enhancement Mode Power MOSFET

### Description

EMR13N03M uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Features

- $V_{DS} = 30V$ ,  $I_D = 12.5A$   
 $R_{DS(on)} < 11m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(on)} < 13.5m\Omega$  @  $V_{GS} = 4.5V$
- Green Device Available
- High Power and Current Handling Capability
- MSL1

### Applications

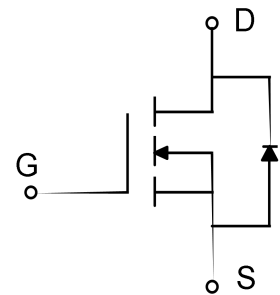
- Battery Protection
- Power Management
- Load Switch

### Absolute Maximum Ratings

| Parameter                                        |                     | Symbol         | Value      | Unit       |
|--------------------------------------------------|---------------------|----------------|------------|------------|
| Drain-Source Voltage                             |                     | $V_{DS}$       | 30         | V          |
| Gate-Source Voltage                              |                     | $V_{GS}$       | $\pm 12$   | V          |
| Continuous Drain Current <sup>1</sup>            | $T_A = 25^\circ C$  | $I_D$          | 12.5       | A          |
|                                                  | $T_A = 100^\circ C$ |                | 7.5        |            |
| Pulsed Drain Current <sup>2</sup>                |                     | $I_{DM}$       | 38         | A          |
| Single Pulse Avalanche Energy <sup>3</sup>       |                     | EAS            | 31.2       | mJ         |
| Avalanche Current                                |                     | $I_{AS}$       | 25         | A          |
| Total Power Dissipation <sup>4</sup>             | $T_A = 25^\circ C$  | $P_D$          | 1.71       | W          |
| Operating Junction and Storage Temperature Range |                     | $T_J, T_{STG}$ | -55 to 150 | $^\circ C$ |

### Thermal Characteristics

| Parameter                                                | Symbol          | Value | Unit         |
|----------------------------------------------------------|-----------------|-------|--------------|
| Thermal Resistance from Junction-to-Ambient <sup>1</sup> | $R_{\theta JA}$ | 73    | $^\circ C/W$ |



**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

| Parameter                                | Symbol               | Test Conditions                                                                          | Min. | Typ. | Max. | Unit |
|------------------------------------------|----------------------|------------------------------------------------------------------------------------------|------|------|------|------|
| Static Characteristics                   |                      |                                                                                          |      |      |      |      |
| Drain-Source Breakdown Voltage           | V <sub>(BR)DSS</sub> | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA                                             | 30   | -    | -    | V    |
| Gate-body Leakage current                | I <sub>GSS</sub>     | V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±12V                                             | -    | -    | ±100 | nA   |
| Zero Gate Voltage Drain Current          | I <sub>DSS</sub>     | V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V                                              | -    | -    | 1    | μA   |
| Gate-Threshold Voltage                   | V <sub>GS(th)</sub>  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                               | 0.4  | 0.75 | 1    | V    |
| Drain-Source on-Resistance <sup>2</sup>  | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 10V, I <sub>D</sub> = 8A                                               | -    | 8.5  | 11   | mΩ   |
|                                          |                      | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6A                                              | -    | 9.0  | 13.5 |      |
|                                          |                      | V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 4A                                              | -    | 10.3 | 16   |      |
| Dynamic Characteristics                  |                      |                                                                                          |      |      |      |      |
| Input Capacitance                        | C <sub>iss</sub>     | V <sub>DS</sub> = 15V, V <sub>GS</sub> =0V, f = 1.0 MHz                                  | -    | 1430 | -    | pF   |
| Output Capacitance                       | C <sub>oss</sub>     |                                                                                          | -    | 150  | -    |      |
| Reverse Transfer Capacitance             | C <sub>rss</sub>     |                                                                                          | -    | 124  | -    |      |
| Switching Characteristics                |                      |                                                                                          |      |      |      |      |
| Gate Resistance                          | R <sub>G</sub>       | V <sub>DS</sub> = 0V, V <sub>GS</sub> =0V, f = 1MHz                                      | -    | 2.5  | -    | Ω    |
| Total Gate Charge                        | Q <sub>g</sub>       | V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 10A                      | -    | 10   | -    | nC   |
| Gate-Source Charge                       | Q <sub>gs</sub>      |                                                                                          | -    | 3.5  | -    |      |
| Gate-Drain Charge                        | Q <sub>gd</sub>      |                                                                                          | -    | 2.2  | -    |      |
| Turn-on Delay Time                       | t <sub>d(on)</sub>   | V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 10A, R <sub>G</sub> = 3Ω | -    | 8    | -    | nS   |
| Rise Time                                | t <sub>r</sub>       |                                                                                          | -    | 28   | -    |      |
| Turn-off Delay Time                      | t <sub>d(off)</sub>  |                                                                                          | -    | 15   | -    |      |
| Fall Time                                | t <sub>f</sub>       |                                                                                          | -    | 7    | -    |      |
| Drain-Source Body Diode Characteristics  |                      |                                                                                          |      |      |      |      |
| Diode Forward Voltage <sup>2</sup>       | V <sub>SD</sub>      | I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V                                                | -    | -    | 1    | V    |
| Continuous Source Current <sup>1,5</sup> | I <sub>S</sub>       | V <sub>G</sub> = V <sub>D</sub> = 0V , Force Current                                     | -    | -    | 12.5 | A    |

**Notes:**

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 25A$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation

## Typical Characteristics

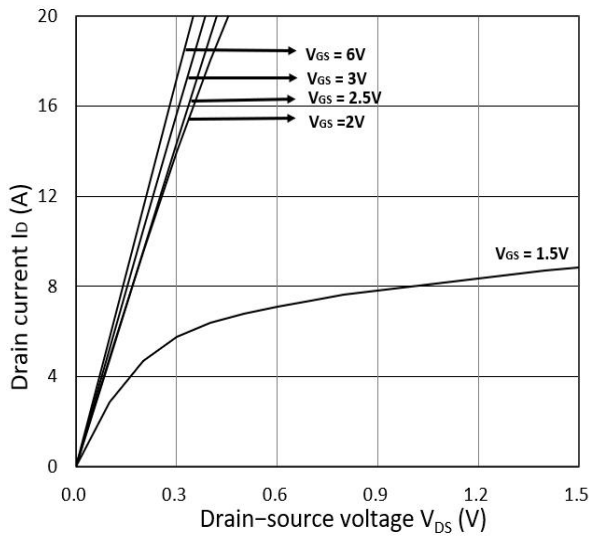


Figure 1. Output Characteristics

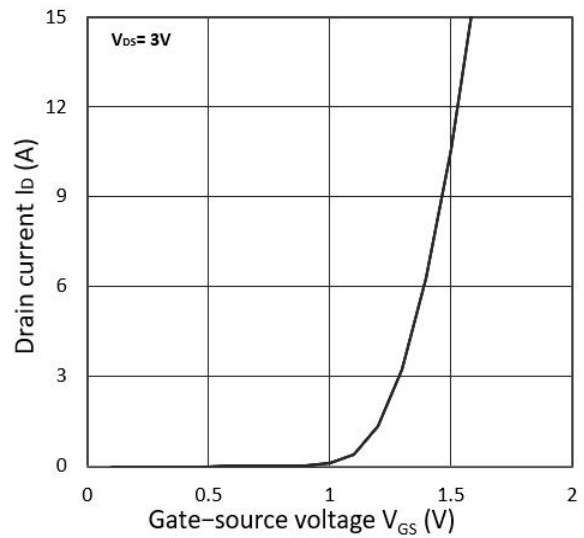


Figure 2. Transfer Characteristic

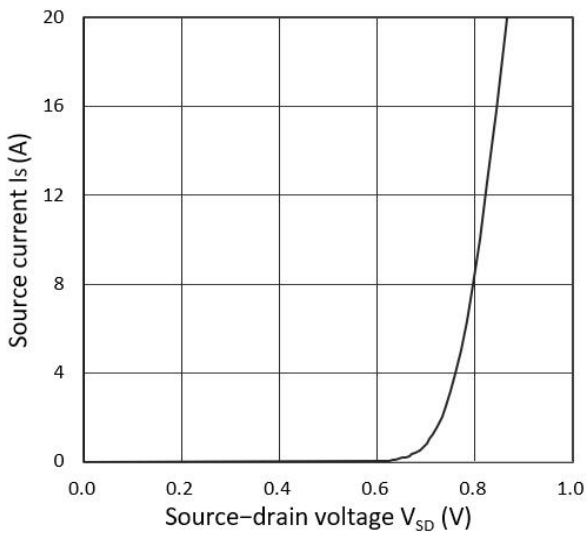


Figure 3. Forward Characteristics of Reverse

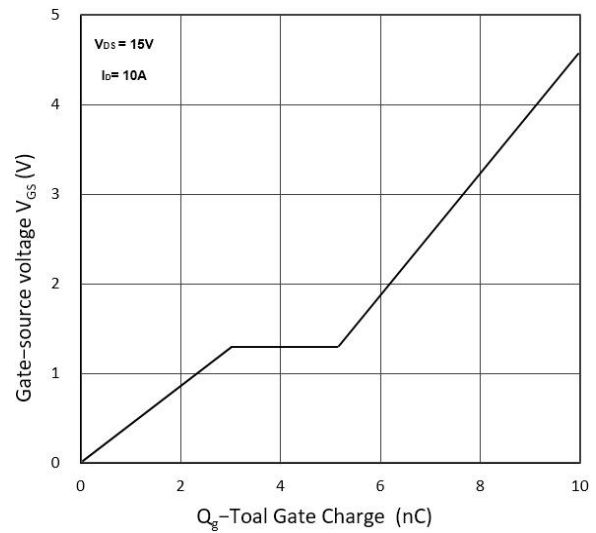


Figure 4. Gate Charge Characteristics

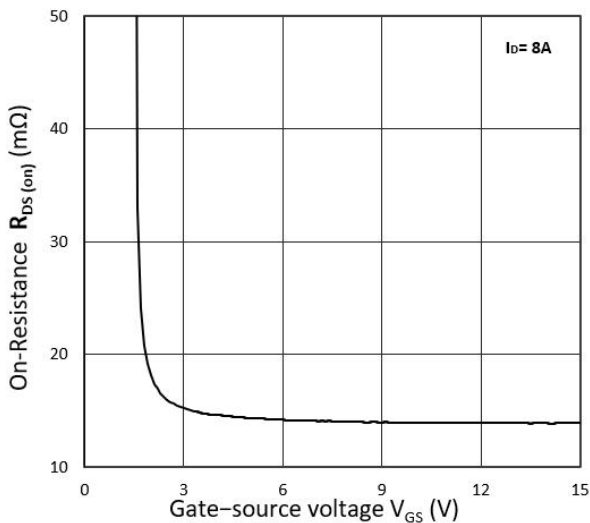


Figure 5.  $R_{DS(on)}$  vs.  $V_{GS}$

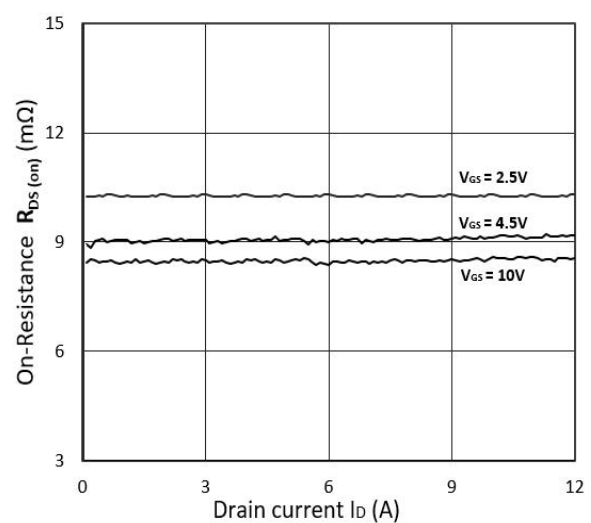


Figure 6.  $R_{DS(on)}$  vs.  $I_D$

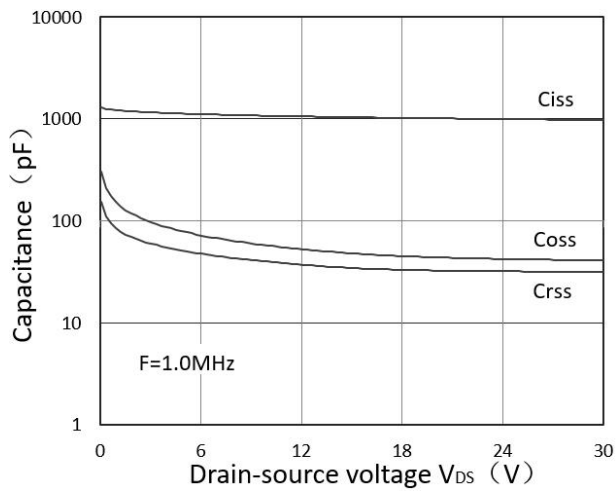


Figure 7. Capacitance Characteristics

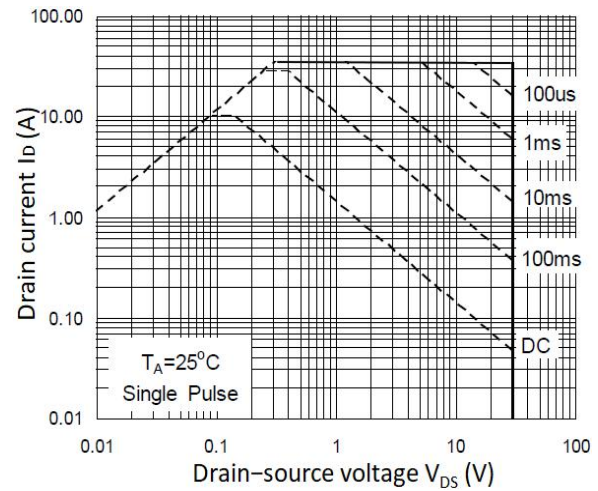


Figure 8. Safe Operating Area

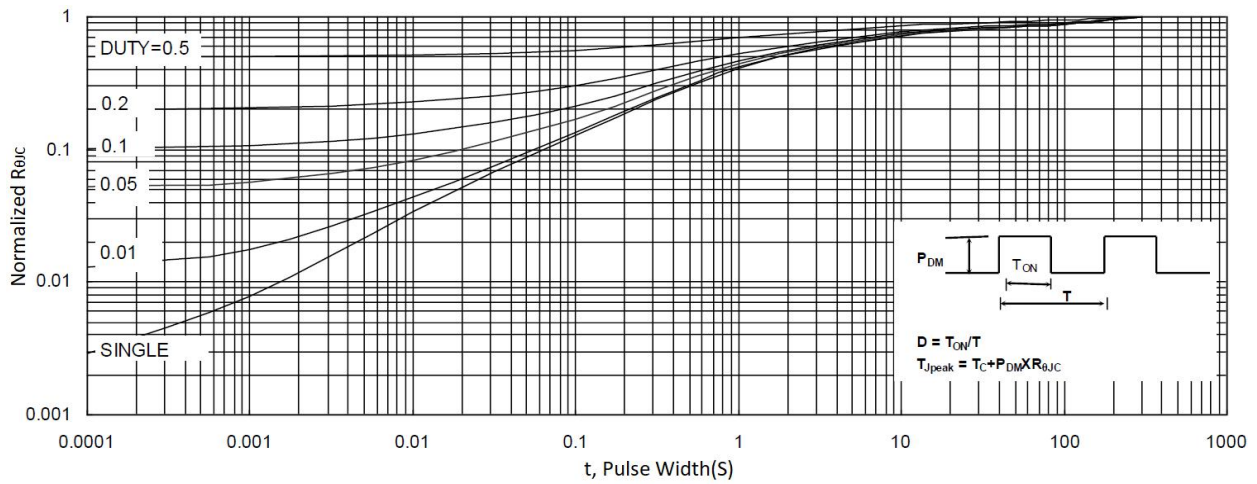


Figure 9. Normalized Maximum Transient Thermal Impedance

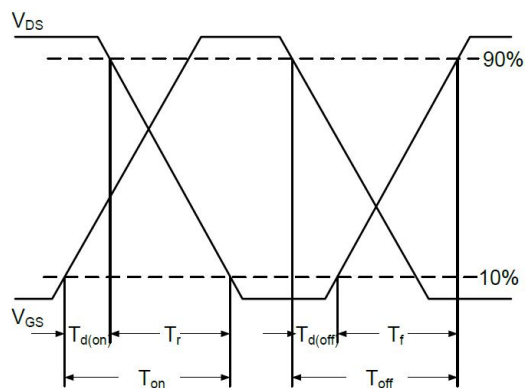


Figure 10. Switching Time Waveform

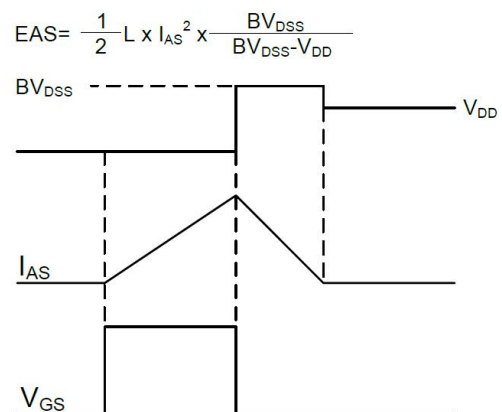
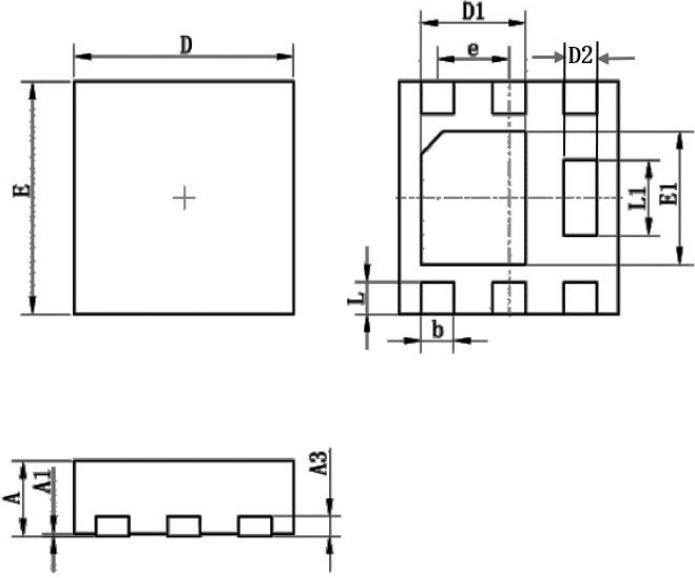


Figure 11. Unclamped Inductive Switching  
Waveform

## Outline Drawing – DFN2020-6L

| Package Outline                                                                   | SYMBOL | MM       |      |
|-----------------------------------------------------------------------------------|--------|----------|------|
|                                                                                   |        | MIN      | MAX  |
|  | A      | 0.5      | 0.6  |
|                                                                                   | A1     | 0        | 0.05 |
|                                                                                   | A2     | 0.152REF |      |
|                                                                                   | b      | 0.25     | 0.35 |
|                                                                                   | D      | 1.95     | 2.05 |
|                                                                                   | D1     | 0.8      | 1    |
|                                                                                   | E      | 1.95     | 2.05 |
|                                                                                   | E1     | 0.8      | 1    |
|                                                                                   | L1     | 0.46     | 0.66 |
|                                                                                   | D2     | 0.25     | 0.35 |
|                                                                                   | e      | 0.65BSC  |      |
|                                                                                   | L      | 0.25     | 0.35 |

## Ordering Information

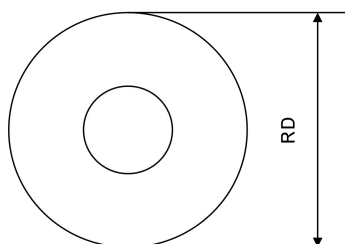
| Part      | Package    | Marking | Packing method |
|-----------|------------|---------|----------------|
| EMR13N03M | DFN2020-6L | R13N03  | Tape and Reel  |

## Marking Information

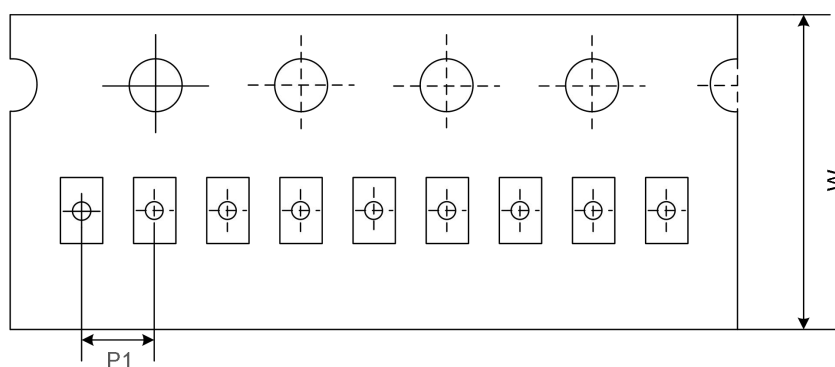
| Part Number | Marking                                                                                                                                      |
|-------------|----------------------------------------------------------------------------------------------------------------------------------------------|
| EMR13N03M   |  <p>R13N03= Device code<br/>WWXXXXX= Tracking Number</p> |

# Tape Information

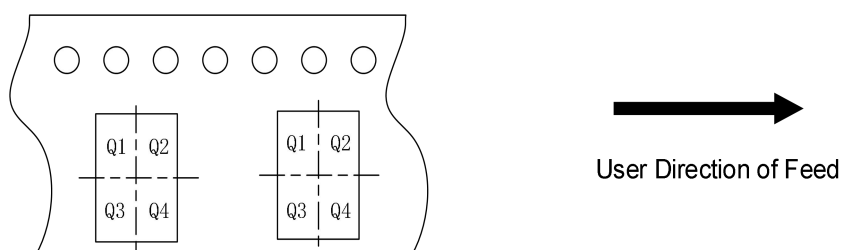
Reel Dimensions



Tape Dimensions

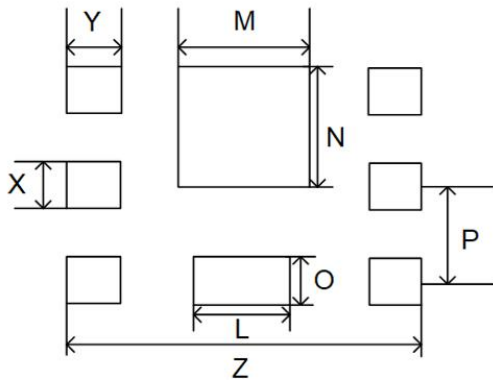


Quadrant Assignments For PIN1 Orientation In Tape



|      |                                         |        |
|------|-----------------------------------------|--------|
| RD   | Reel Dimensions                         | 7 inch |
| W    | Overall width of the carrier tape       | 8 mm   |
| P1   | Pitch between successive cavity centers | 4 mm   |
| Pin1 | Pin1 Quadrant                           | Q2     |

## DFN2020-6L RECOMMENDED LAND PATTERN



| DIMENSIONS |       |
|------------|-------|
| SYMBOL     | MM    |
| X          | 0.40  |
| Y          | 0.425 |
| M          | 1.15  |
| N          | 0.95  |
| L          | 0.80  |
| O          | 0.48  |
| P          | 0.65  |
| Z          | 2.30  |

Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.050\text{mm}$ .
3. The pad layout is for reference purposes only.

## Revision History

| No. | Version | Date       | Revision Item                                     | Request    | Function and characteristic checking | Package dimension checking | Typos checking |
|-----|---------|------------|---------------------------------------------------|------------|--------------------------------------|----------------------------|----------------|
| 1   | 1.0     | 2020-09-22 | Released Version                                  | Qi Shu Kun | Qi Shu Kun                           | Liu Jia Ying               | Liu Jia Ying   |
| 2   | 1.1     | 2020-11-4  | Add Tape information and recommended land pattern | Qi Shu Kun | Qi Shu Kun                           | Liu Jia Ying               | Liu Jia Ying   |
| 3   | 1.2     | 2021-3-19  | Update Package size, marking and Qg graph         | Qi Shu Kun | Qi Shu Kun                           | Liu Jia Ying               | Liu Jia Ying   |
| 4   | 1.3     | 2021-6-23  | Update recommended land pattern                   | Qi Shu Kun | Qi Shu Kun                           | Liu Jia Ying               | Liu Jia Ying   |
| 5   | 1.4     | 2021-8-19  | Update PIN1 Direction                             | Qi Shu Kun | Qi Shu Kun                           | Liu Jia Ying               | Liu Jia Ying   |